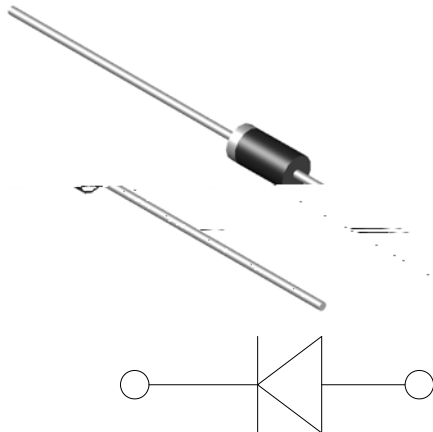


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- High efficiency
- High current capability
- High Reliability
- High surge current capability
- Glass passivated chip junction
- Solder dip 275 °C max. 7 s, per JESD 22-B106

€ Ñi•W (A

- DO-204AC(DO-15)
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- : Tin plated leads, solderable per

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	RRM	V	50	100	200	300	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V	35	70	140	210	280	420	560	700
Maximum DC blocking Voltage	V _{DC}	V	50	100	200	300	400	600	800	1000

Average Forward Current
@60Hz sine wave, Resistance load, Ta=75

I_{F(AV)}@Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C Cj pF 28 17 12

Storage Temperature	T _{stg}									
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					*					
Maximum instantaneous forward voltage drop per diode	V _F	V	I _{FM} =2.0A	1.0	1.3	1.7				
Maximum DC reverse current at rated DC blocking voltage per diode	I _R	μA	T _j =25	2.5						
			T _j =125	100						
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A, I _R =1.0A, I _m =0.25A	50		75				



